



Advanced Electronic Packaging Technology

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Message from the Guest Editor

Dear Colleagues,

As Moore's Law is reaching its limitation, the development of advanced packaging is moving towards advanced system integration in order to achieve more function, lower cost and smaller form factor. Advanced packaging brings the heterogeneous integration of various front-end technology nodes and higher levels of customization down both the scaling and functional roadmap. Recently, new technologies, such as TSV (Through Silicon Via), Wafer-level Fan-out (WL-FO) and 3D IC stacking, are fast growing and play important roles in the applications of advanced system integration.

In this Special Issue, the recent progress on advanced packaging technologies will be presented including WLP, 3D IC, 2.5D Interposer, TSV, TGV, Fan-Out, Flip-Chip, 3D WLCSP, Hybrid bonding, Panel-level packaging, etc.

Prof. Dr. Daquan Yu

Guest Editor





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Message from the Editor-in-Chief

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